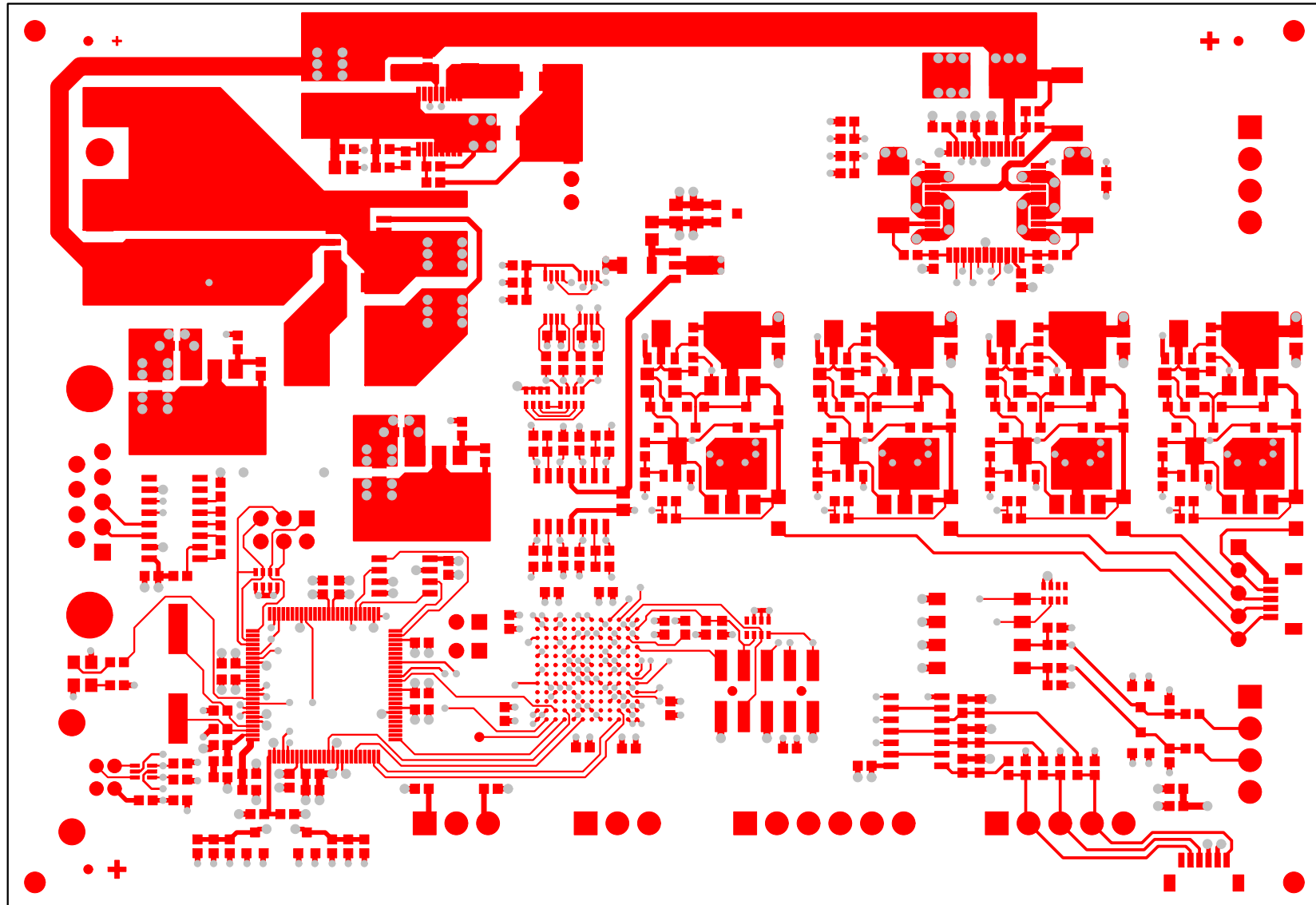
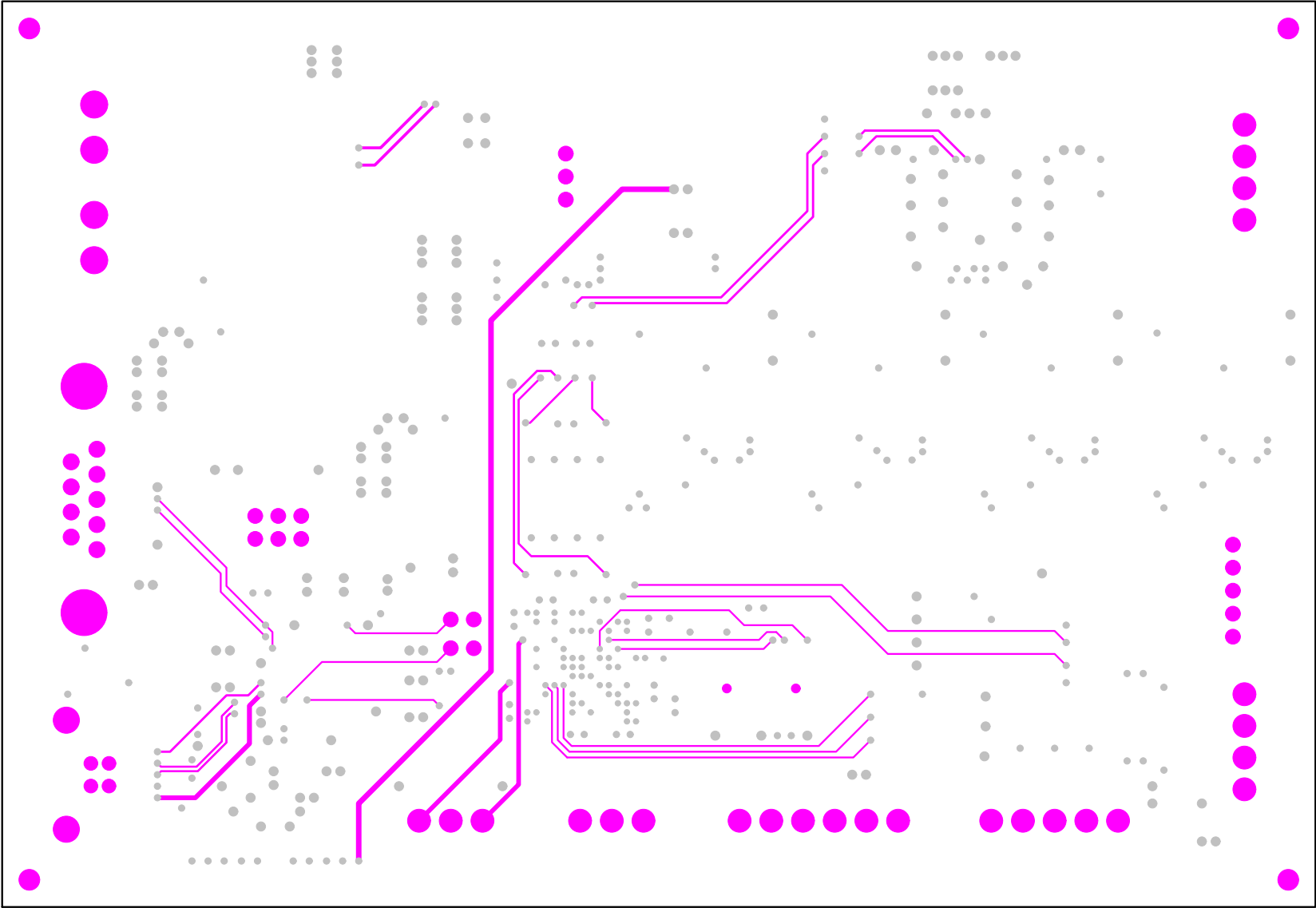


ROUTING TOP(L1) 145x100MM

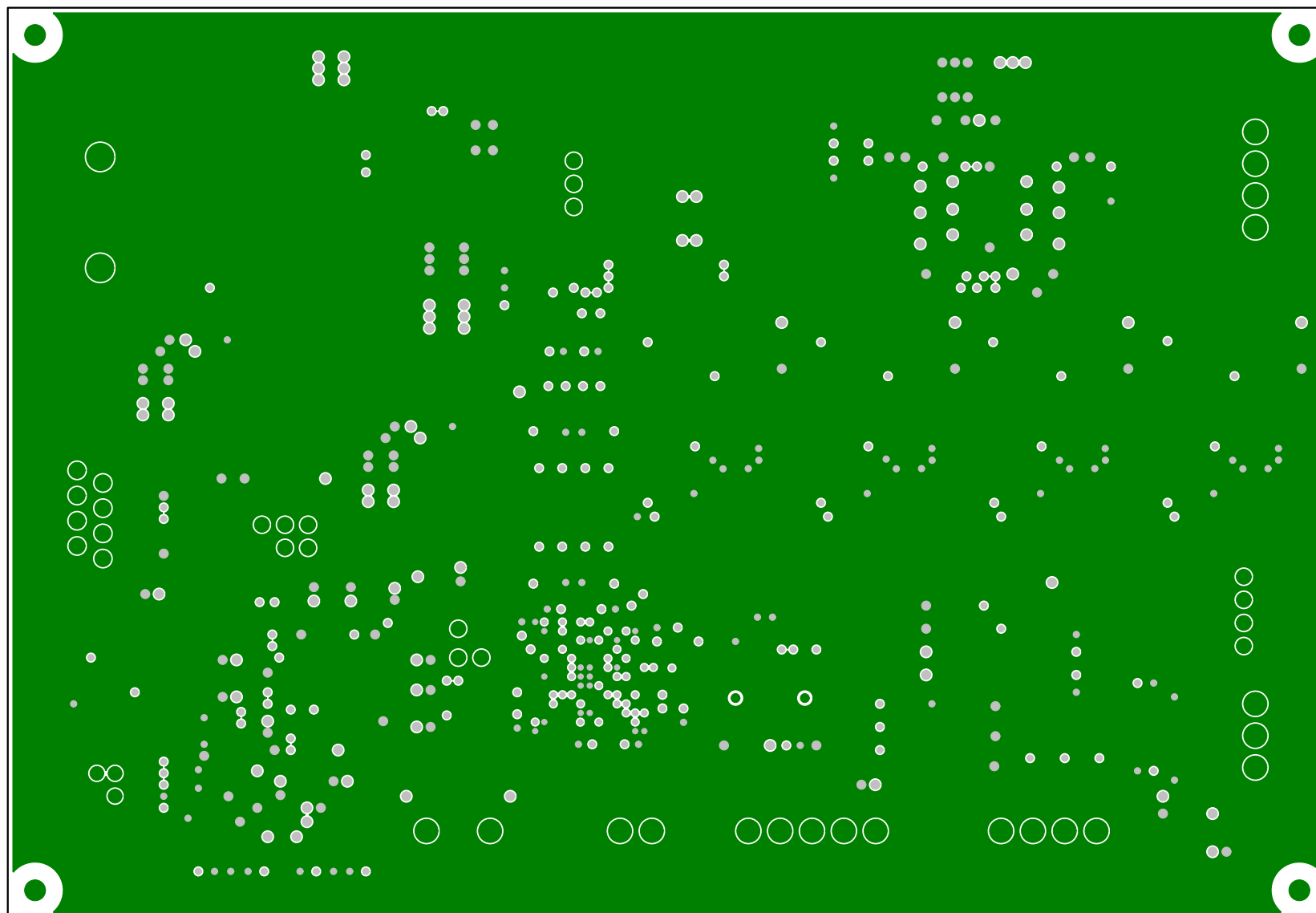


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ROUTING INNER LAYER 2 (L2)

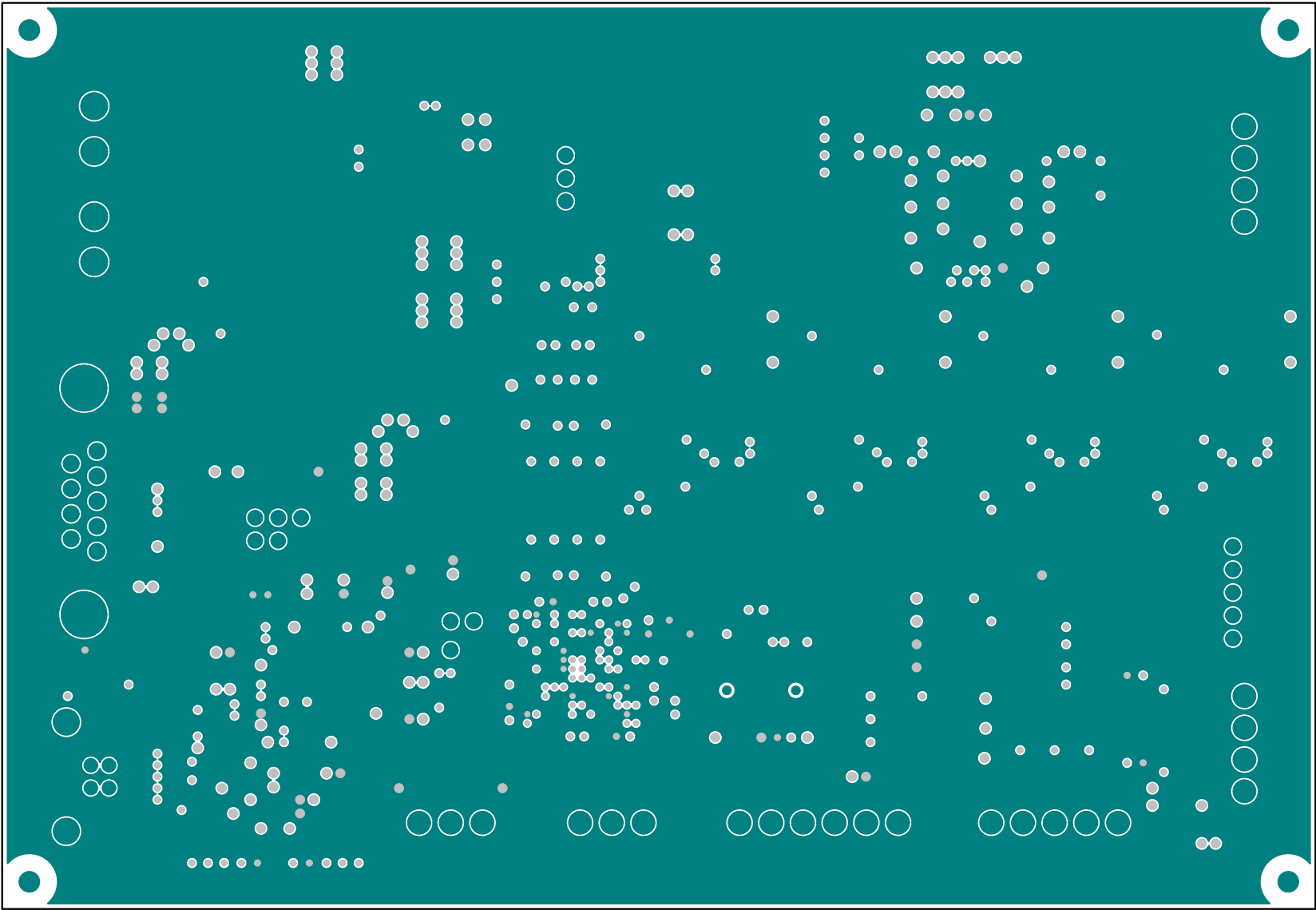


GROUND LAYER 3 (L3)

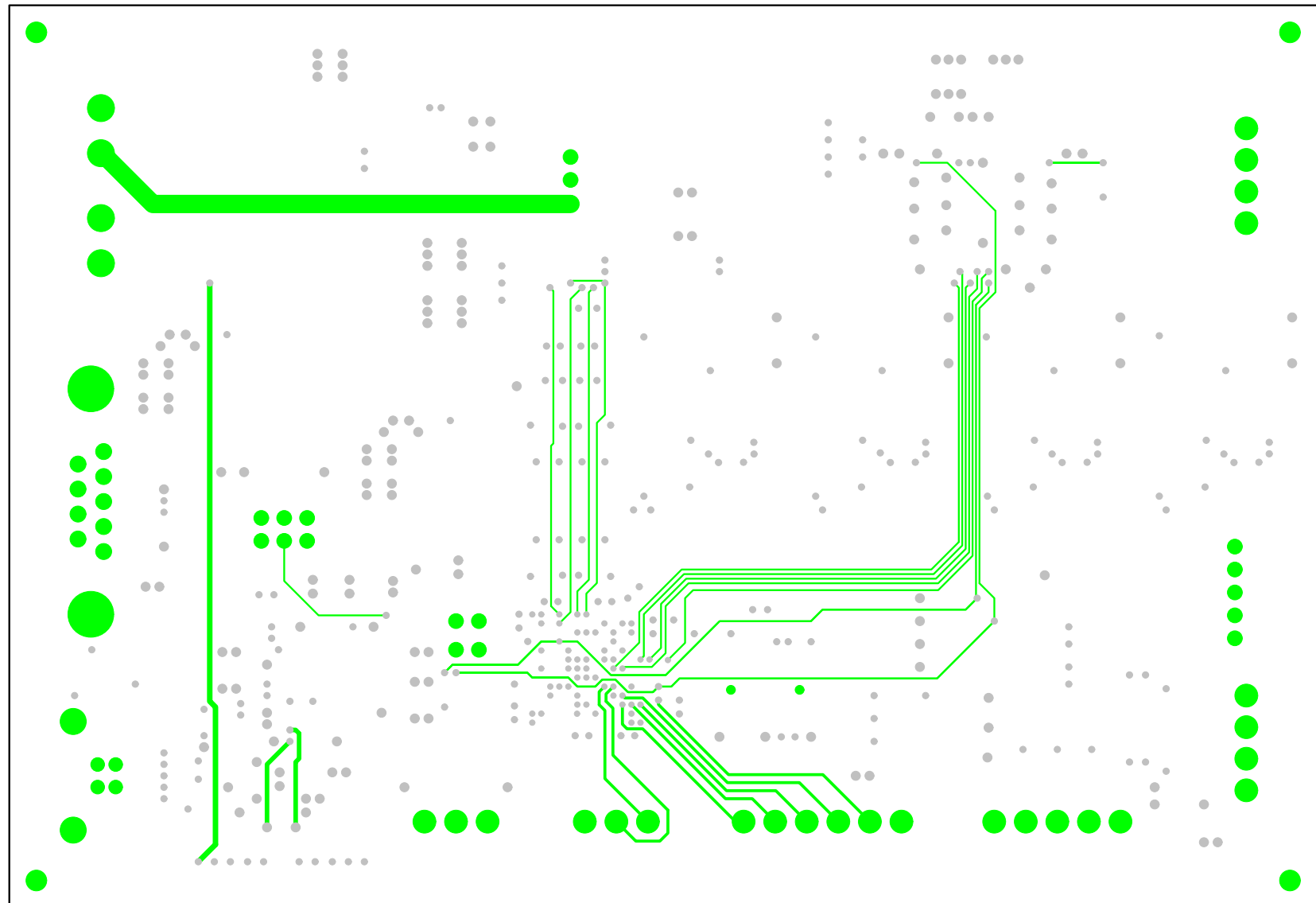


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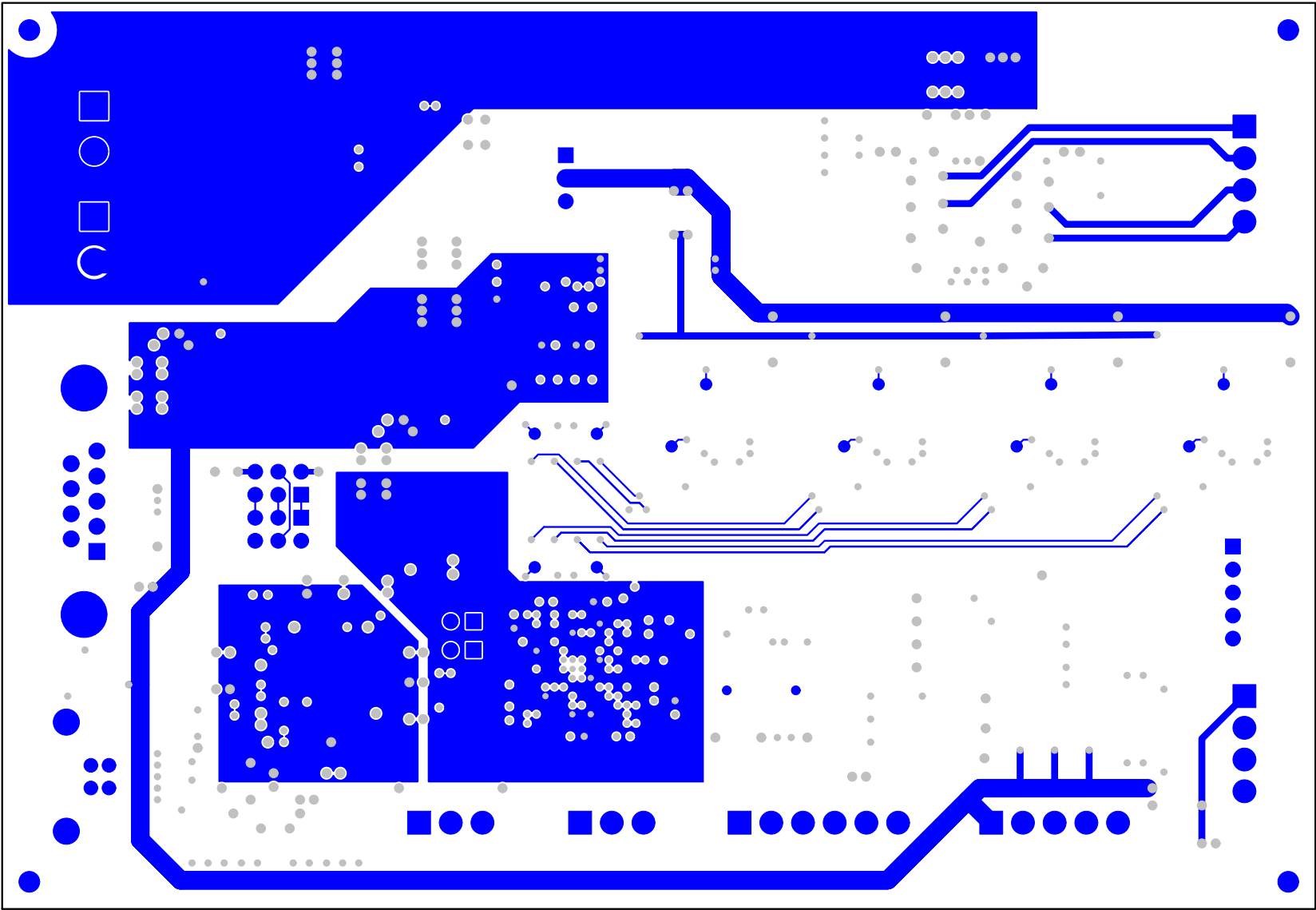
POWER LAYER 4 (L4)



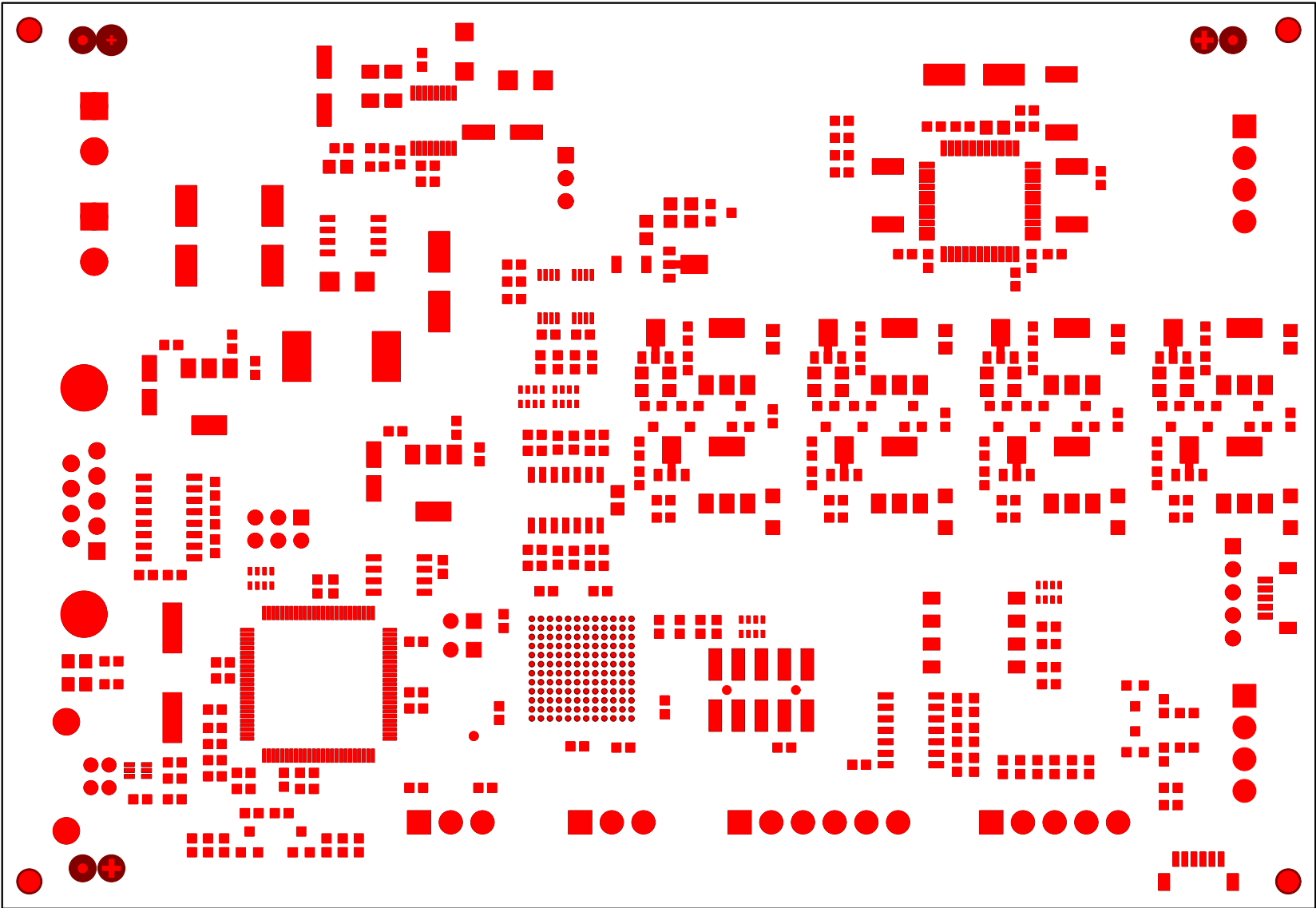
ROUTING INNER LAYER 5 (L5)



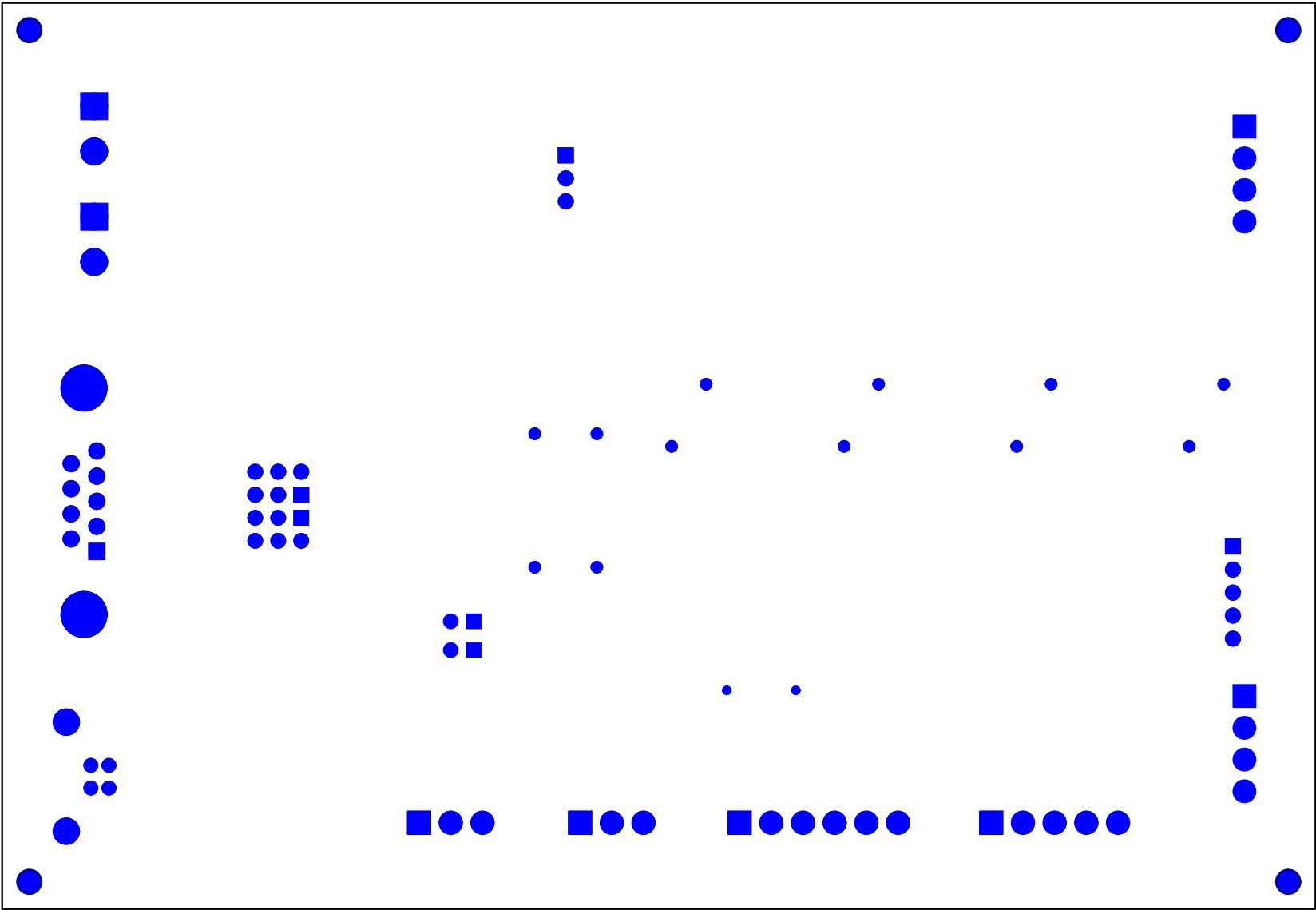
(aJ) MOTTOR ɹɹɹɹɹ



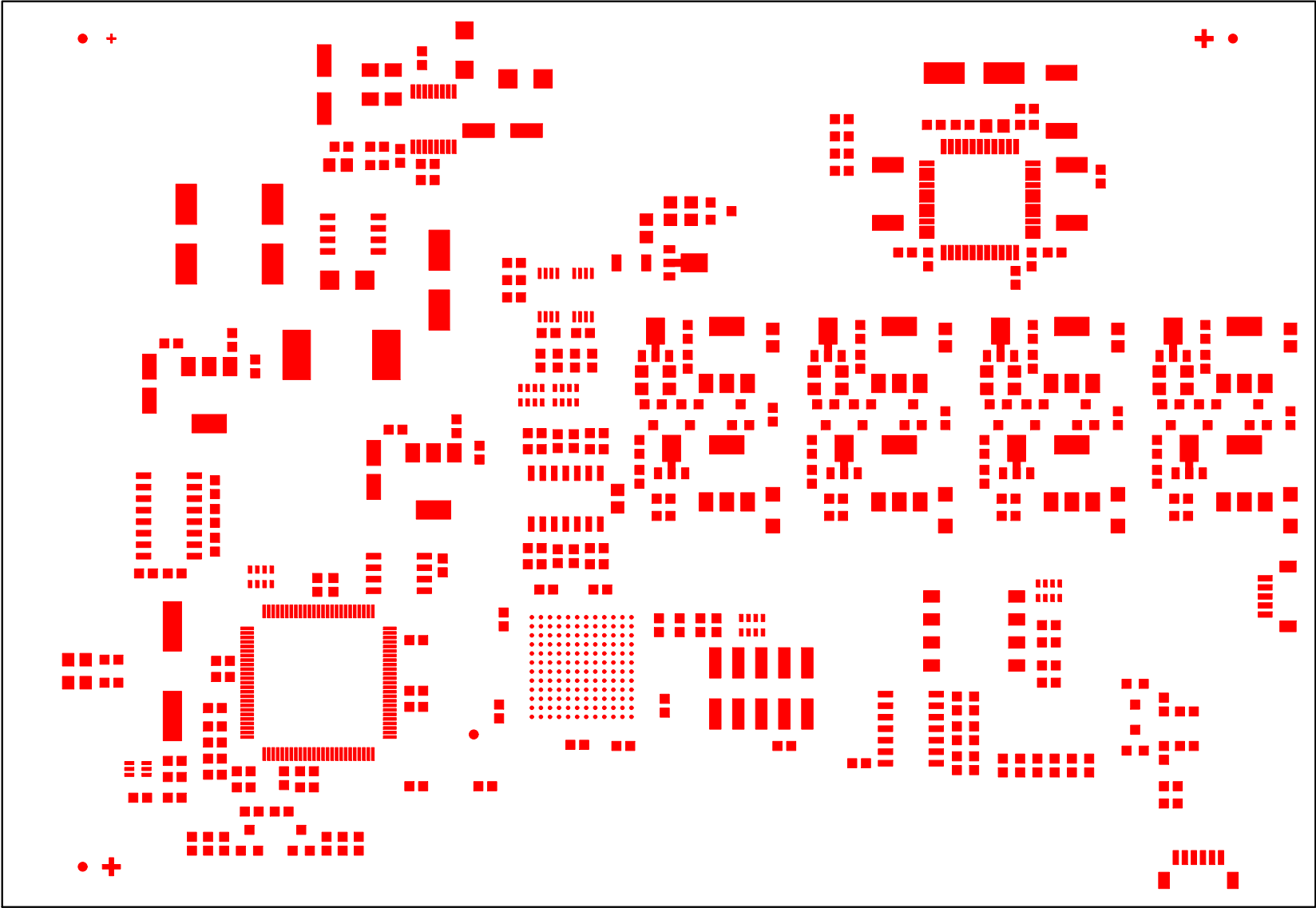
SOLDER MASK TOP (L21)



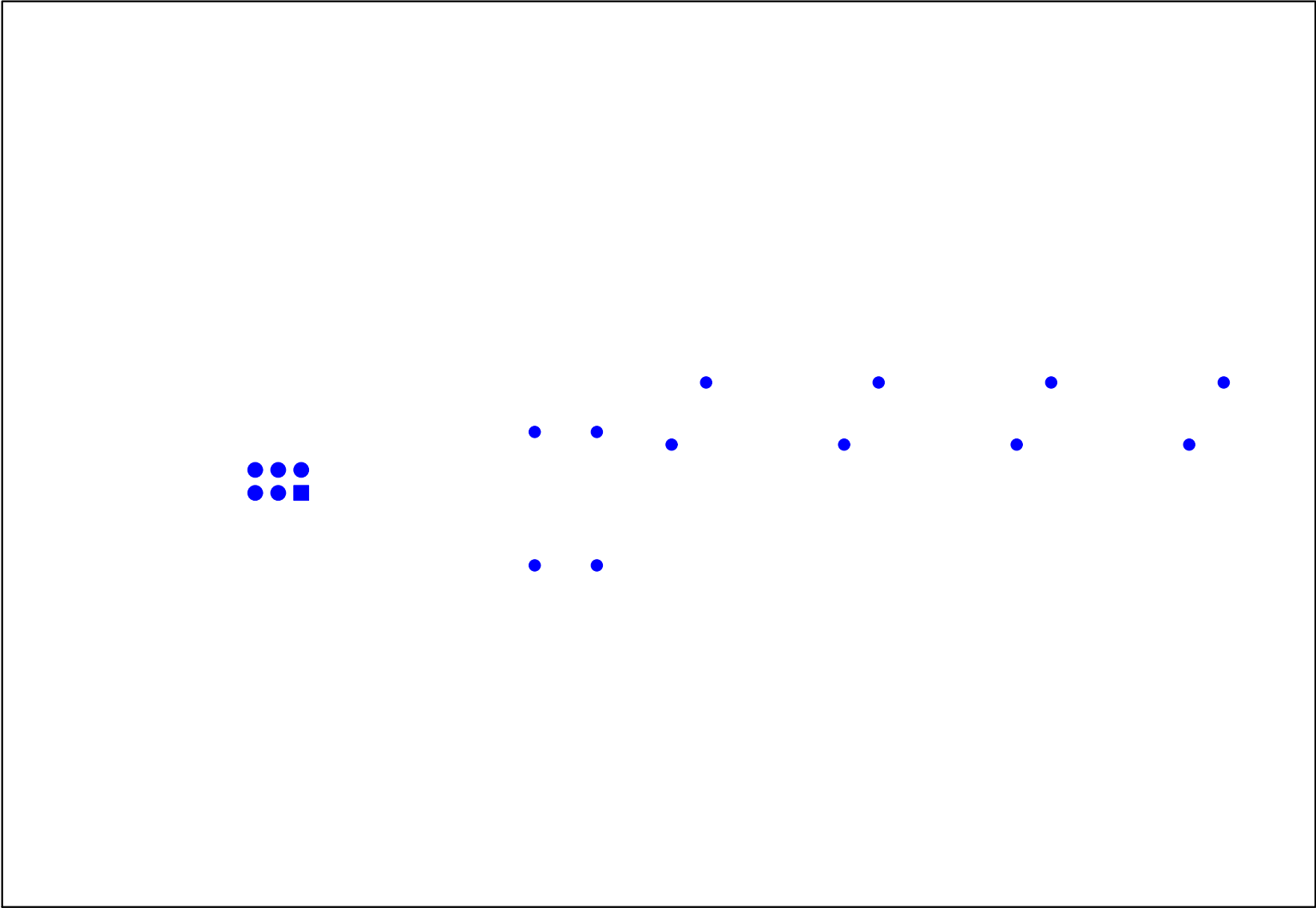
(T38) 20LDER MASK BOTTOM X2AM ЯEOLJ02



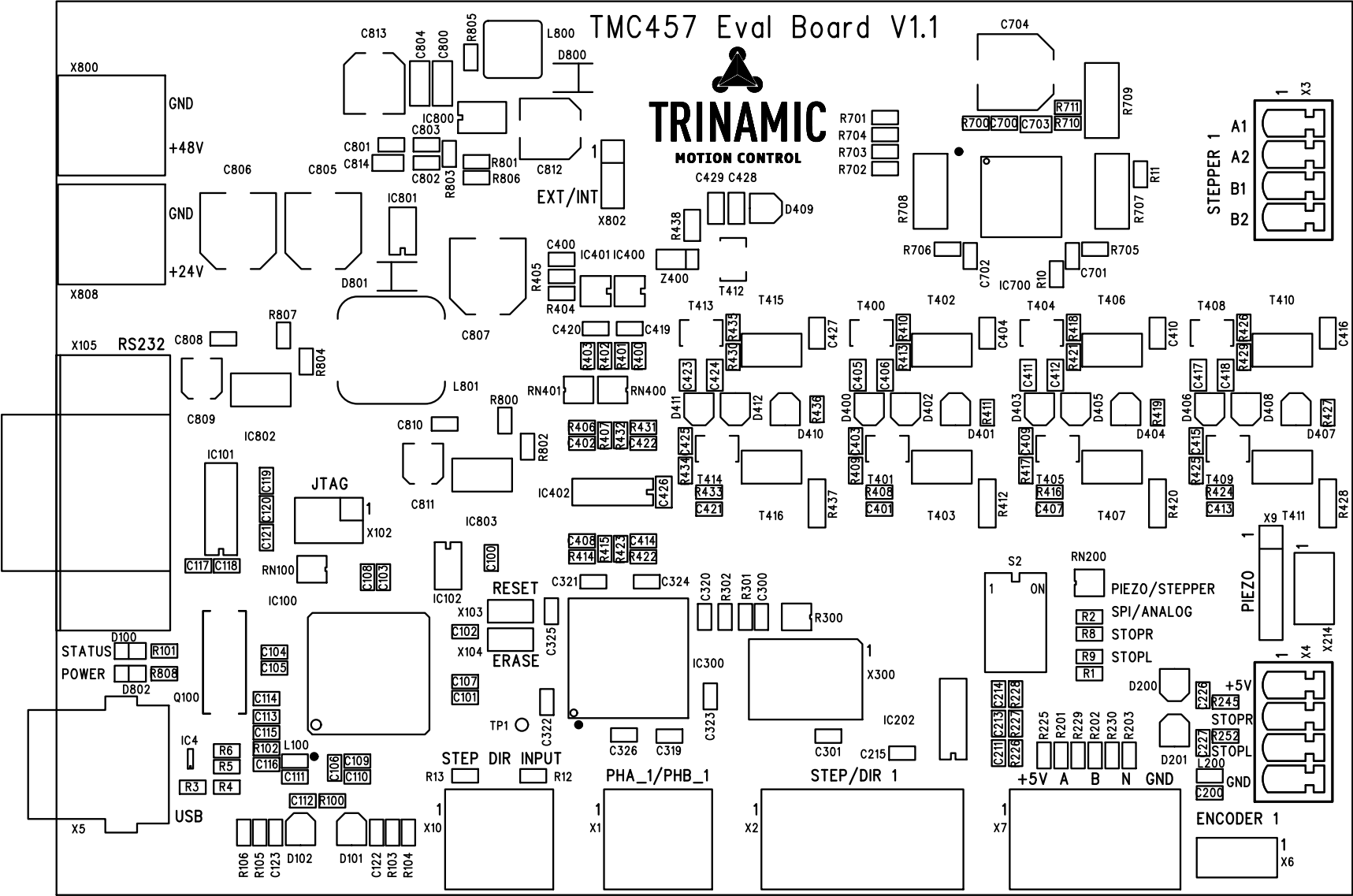
PASTE MASK TOP(L23)

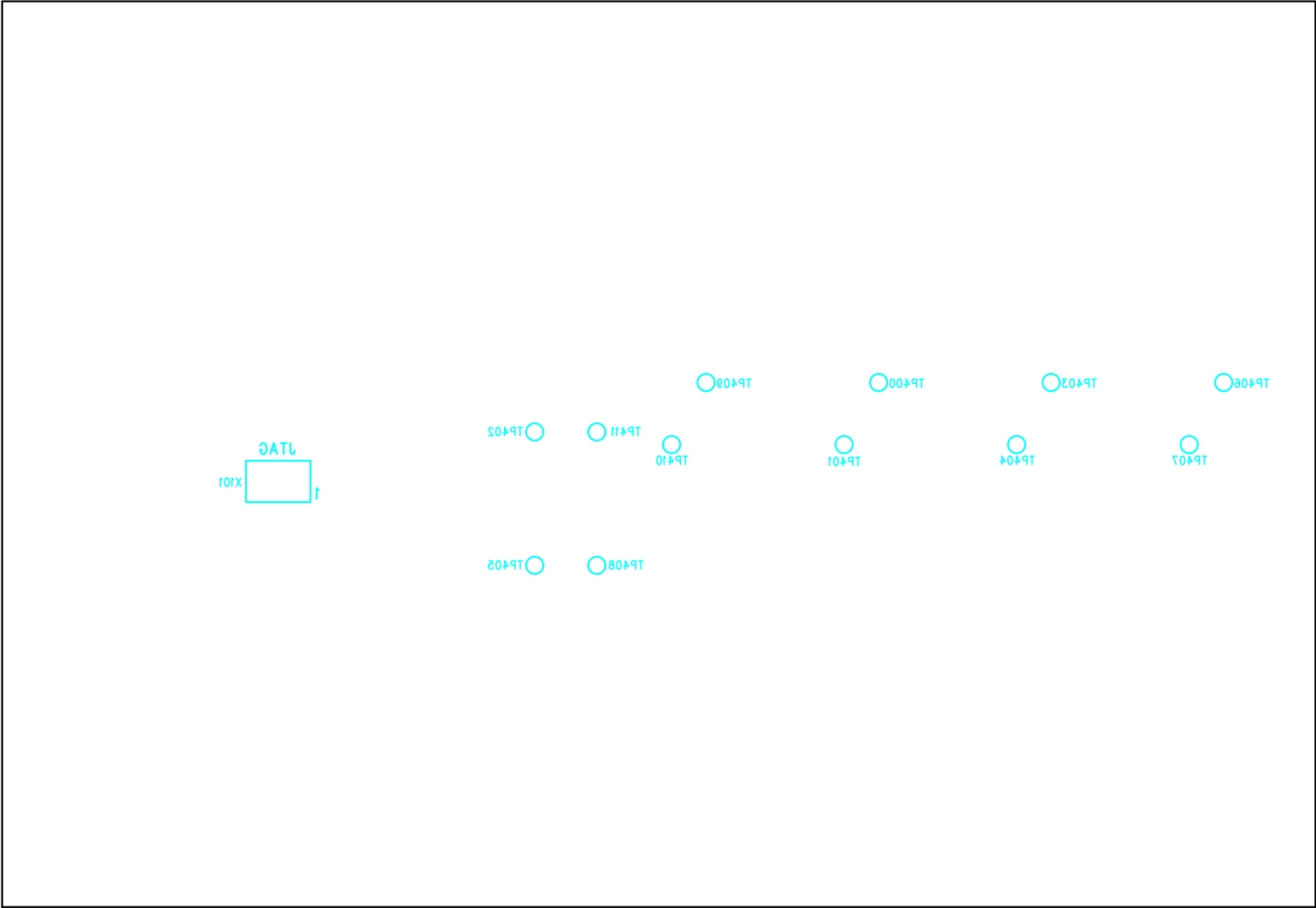


PASTE MASK BOTTOM (TSS)

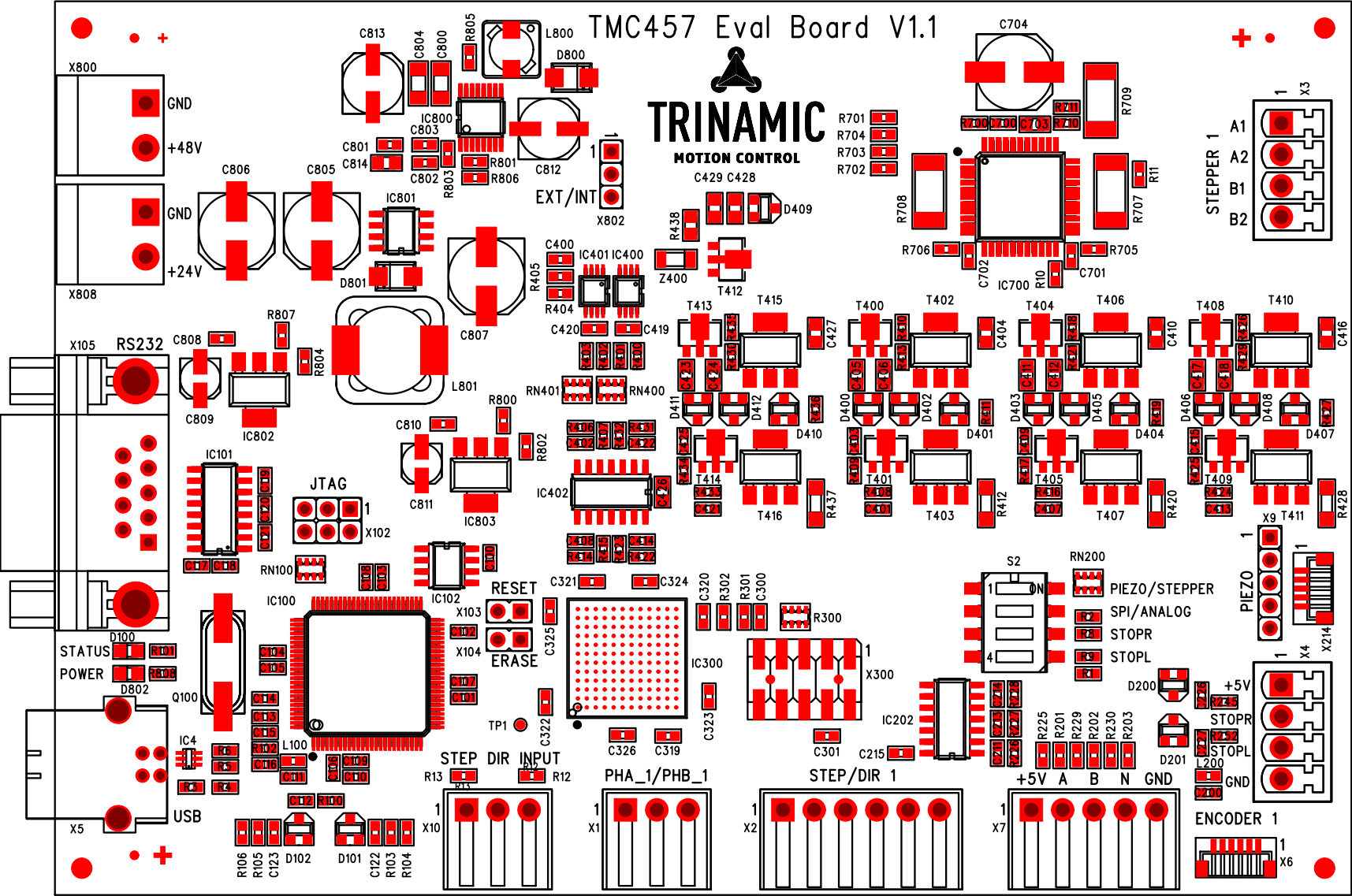


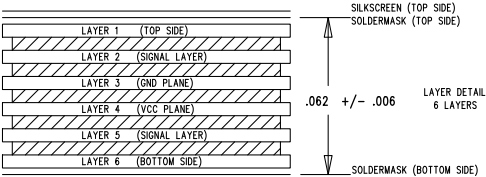
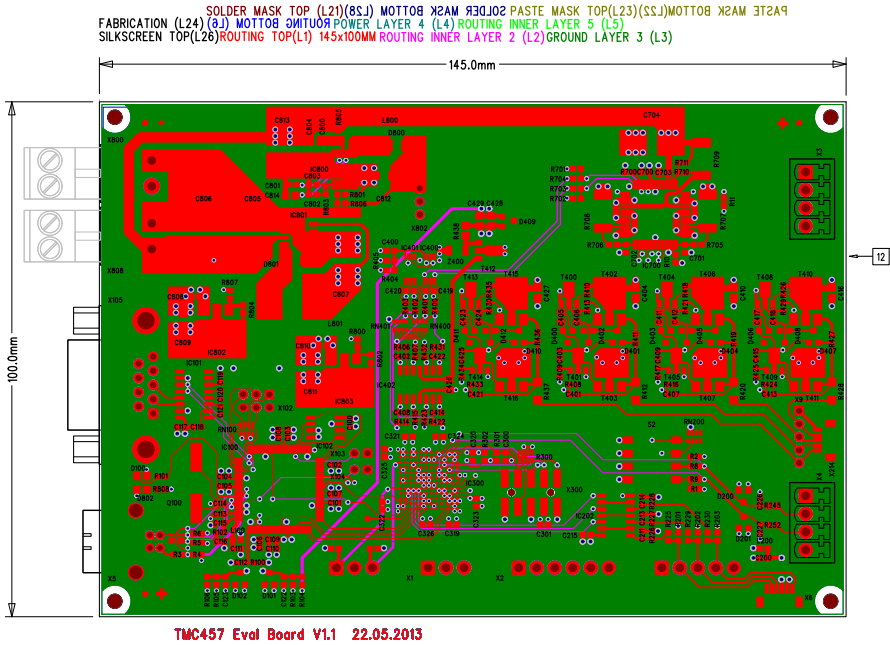
SILKSCREEN TOP(L26)





SILKSCREEN TOP(L26)ROUTING TOP(L1) 145x100MM





- NOTES : (UNLESS SPECIFIED OTHERWISE.)
- 1) ALL DIMENSIONS ARE IN INCHES.TOLERANCE IS +/- 0.005 CONFORMING TO IPC-A-600. GIVEN MECHANICAL DIMENSIONS ARE IN MILLIMETRES.
 - 2) HOLE SIZES ARE SPECIFIED IN THOUSANDTHS. HOLE SIZES APPLY AFTER PLATING. HOLE SIZE TOLERANCE TO BE +/- 0.003 UNLESS SPECIFIED OTHERWISE. PLATING TO BE 0.0010 MINIMUM.
 - 3) MATERIAL : FR-4-2 NATURAL EPOXY/FIBERGLASS
1 OZ. COPPER ON ALL LAYERS.
2 SIDES PLATED.
FINISHED THICKNESS : $0.062 \pm \frac{0.006}{0.006}$
 - 4) APPLY SOLDERMASK OVER BARE COPPER, BOTH SIDES. FINISH ALL EXPOSED COPPER SURFACES WITH STANDARD LEADFREE SURFACE.
 - 5) THE LOCATION OF THE MARKING SHOULD BE ON THE SURFACE OF THE PCB, NOT THE EDGE.
 - 6) APPLY SOLDERMASK TO COMPONENT SIDE AND SOLDER SIDE, USING
☐ PC401 OR EQUIVALENT.
☒ LIQUID PHOTO IMAGEABLE.
☐ DRY FILM. COLOR : GREEN. USE SEPARATE FILM FOR COMPONENT SIDE AND SOLDER SIDE SOLDERMASKS. FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO SOLDERMASK PHOTOPLT FILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
 - 7) APPLY LEGEND TO BOTH SIDE USING NON-CONDUCTIVE EPOXY INK. COLOR : WHITE. FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PHOTOPLT FILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
 - 8) PCB SHALL BE CLEAN AND FREE FROM DIRT, OIL, FINGERPRINTS, CORROSION, AND ANY OTHER FOREIGN MATERIAL.
 - 9) MODIFIED PHOTOPLT FILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
 - 10) FABRICATOR HAS APPROVAL TO REMOVE NON-FUNCTIONAL PADS FROM INNER LAYERS.
 - 11) BOW AND TWIST SHALL BE LESS THAN 0.0075" PER INCH.
 - 12) ALL PRINTED CIRCUIT BOARD NETS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. MARK TEST VERIFICATION STAMP APPROXIMATELY WHERE SHOWN, ALONG EDGE OF PCB, USING WHITE INK.
 - 13) FABRICATION OF P.W.B. TO COMPLY WITH IPC-A-600, CLASS II , CURRENT REVISION.

APPROVALS		DATE	TRINAMIC			
DRAWN: Eli Puusepp		22.05.2013	TMC457 Evaluation Board V1.1 FABRICATION			
CHECKED:						
PROJ MGR: Kaido Kevvai		22.05.2013				
CLIENT: TRINAMIC		SIZE B	DRAWING NUMBER 8707000311	SCALE 1 : 1	SHEET 1 OF 1	REVISION V1.1

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